



Practical Guide to the Packaging of Electronics: Thermal and Mechanical Design and Analysis (Hardback)

By Ali Jamnia

Taylor Francis Inc, United States, 2009. Hardback. Book Condition: New. 2nd Revised edition. 236 x 157 mm. Language: English. Brand New Book. As the demand for packaging more electronic capabilities into smaller packages rises, product developers must be more cognizant of how the system configuration will impact its performance. Practical Guide to the Packaging of Electronics: Second Edition, Thermal and Mechanical Design and Analysis provides a basic understanding of the issues that concern the field of electronics packaging. First published in 2003, this book has been extensively updated, includes more detail where needed, and provides additional segments for clarification. This volume supplies a solid foundation for heat transfer, vibration, and life expectancy calculations. Topics discussed include various modes of heat removal, such as conduction, radiation, and convection; the impact of thermal stresses; vibration and the resultant stresses; shock management; mechanical, electrical, and chemically induced reliability; and more. Unlike many other available works, it neither assumes the reader s familiarity with the subject nor is it so basic that the reader may lose interest. Dr. Ali Jamnia has published a large number of engineering papers and presentations and is the holder of a number of patents and patent applications. He...



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I just started off reading this article publication. This really is for all who statte there had not been a really worth looking at. You will not feel monotony at anytime of your own time (that's what catalogs are for about should you ask me).

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